OSD335x Family

Rev. 3 2/29/2016

Introduction

The OSD335x Family of System-In-Package (SIP) products are building blocks designed to allow easy and cost-effective implementation of systems based on Texas Instruments' powerful Sitara™ AM335x line of processors. The OSD335x integrates the AM335x along with the TI TPS65217C PMIC, the TI TL5209 LDO, up to 1 Gigabyte of DDR3 Memory, and over 140 resistors, capacitors, and inductors all into a single design-in-ready package.

With this level of integration the OSD335x Family of SIPs allows designers to focus on the key aspects of their system without spending time on the complicated high-speed design of the processor/DDR3 interface. It also reduces the overall size and complexity of the design. The OSD335x can significantly decrease the time to market for AM335x-based products.

Features

- TI AM335x, TPS65217C, TL5209, DDR3, and over 140 Passive components integrated into a single package
- TI AM335x Features:
    - ARM® Cortex®-A8 up to 1GHz
    - 8 channel 12-bit SAR ADC
    - Ethernet 10/100/1000 x 2
    - USB 2.0 HS OTG + PHY x2
    - MMC, SD and SDIO x2
    - LCD Controller and 3D Graphics Engine
- Access to All AM335x GPIOs and Peripherals
- Up to 1GB DDR3
- PWR In from USB or Li-Ion Battery
- PWR Out: 1.8V, 3.3V and SYS

Figure 1. OSD335X Block Diagram

Benefits

- Integrates over 140 Components into one
- Compatible with AM335x Development tools and software
- Wide BGA ball pitch allows for low-cost assembly.
- Significantly Reduces Design Time
- Decreases Layout Complexity
- Saves board space
- Increased Reliability through reduced number of components
- Power Savings
    - shorter signal trace lengths,
    - reduced parasitics,
- 400 Ball BGA (20 X 20)
- 1.27mm pitch
- 27mm X 27mm package size
- Temp Range: 0 to 90°C

For More Information

- Contact Octavo Systems at osd335@octavosystems.com